TEKNOFLOOR AQUA DUST BINDER 0440-00



Water-borne wood dust binder for the production of fillers for interior use

TEKNOFLOOR AQUA DUST BINDER 0440-00 is a water-borne, viscoplastic wood dust binder (joint filler solution) for the production of fillers and "liquid wood". The product is characterised by its fast-drying properties and good sandability.

TECHNICAL DATA

Certificates, approvals and classification	Swiss environmental label UE II, class B, EMICODE EC 2
Fields of application	Floors
Recommended substrate	Wood
Solids	Approx. 12% by weight
Volatile organic compound (VOC)	Approx. 50 g/l (DIRECTIVE 2010/75/EU) The VOC value provided is the average value for factory produced products, and consequently it will be subject to variations between individual products covered by this Technical Data Sheet.
Colours	Colourless.
Density	Approx. 1.01 g/ml
Storage	Storage temperature is +5°C - +30°C. Store in a tightly closed container.

DIRECTION FOR USE

Surface preparation	Every substrate must be well-cleaned, dry and free from grease and oil. Coating removal: Sand

Application method	Filling knife Only use up to a maximum joint width of 2 mm. Put the TEKNOFLOOR AQUA DUST BINDER 0440-00 in a container, stir in the wood sanding dust with a spatula. Depending on the desired consistency, add wood dust or TEKNOFLOOR AQUA DUST BINDER 0440-00. Mixing ratio: Mix 15-20 g of wood dust with 100 g of the wood dust binder. Required quantity: 40-50 g of the wood dust mixture is sufficient for an area of approx. 1 m². The required quantity can vary significantly depending on the type and extent of joints and dents. Trowel-fill, sand. Can subsequently be reworked with all parquet floor primers and/or all water-soluble parquet coating systems, oils as well as all solvent-based parquet floor sealing coatings. Does not cause discolouration on the wood.
Application	Stir or shake the product well for several minutes before use, if necessary by machine.

APPLICATION ADVICE		
Raw parquet flooring		
	Product	
Smoothing	TEKNOFLOOR AQUA DUST BINDER 0440-00 (mix 15-20 g wood dust with 100 g wood dust binding agent)	ca. 40-50 g mixture/m² depending on the type and size of the joints and dents

Application conditions	Recommended temperature for surroundings and product: +15°C-25°C. Do not apply below +10°C. Ideal surface and object temperature for application: +18°C-22°C. Avoid application in direct sunlight. Underfloor heating systems must be adjusted well in advance.
Drying time	+23°C / 65% RH
- dust free	60 min
- overcoatable	1-2 h
- fit for sanding	1-2 h
Cleaning	Wash the equipment immediately after use. VERDÜNNER 1000-98

HEALTH AND SAFETY

Safety and precaution measures	See safety data sheet.
First aid	We recommend wearing personal protective clothing even in cases where no local regulations are in force. CH: The precautions according to local regulations (SUVA) with respect to hygiene and equipment must be observed.

ADDITIONAL INFORMATION

Maintenance instructions

For more information on wood floor surface treatments and their use, visit www.parkett-verband.ch.

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